



## Product Specification

|              |                              |
|--------------|------------------------------|
| Product:     | <b>Conductive Gold Paste</b> |
| Part Number: | <b>54H-1803</b>              |

### Application Scope :

This product is suitable for alumina ceramic products, sensors, and other electrodes.

### Usage Conditions :

|                  |  |
|------------------|--|
| Substrate        | Alumina ceramic  |
| Printing         | 200-300 mesh screen printing   |
| Leveling         | Level at room temperature for 5-15 minutes (depending on the actual leveling time).  |
| Drying           | Bake in an oven at 100-150°C for 10-15 minutes (if the test temperature is below 300°C, adjust the baking time according to actual conditions).  |
| Firing Condition | Sintering in a tunnel furnace under air atmosphere at a peak temperature of 850±10°C (recommended value) for 9-11 minutes. (The sintering range can be adjusted within 830-850°C according to actual needs, but the peak temperature time must be 10 minutes.) |
| Thinner          | ST-1000  |

### Characteristics :

#### 1. Paste Characteristics :

| Characteristic | Standard    | Test Method And Conditions   |
|----------------|-------------|--|
| 1 Fineness     | ≤5μm        | FOG test   |
| 2 Viscosity    | 130-280Pa.s | Brookfield HBT viscometer (Rotor SC4-14/6R), 10 rpm, with viscosity adjustable to 25±1°C according to user requirements. |

#### 2. Characteristics After Curing :

Under 1 firing condition, the film thickness is 8-12μm

Check fired film produced under the conditions specified in 1) , (Film thickness is 8-12μm.)



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| Characteristics |                  | Standard                       | Test Method And Conditions                                    |
|-----------------|------------------|--------------------------------|---|
| 3               | Resistivity      | $\leq 6\text{m}\Omega/\square$ | Test pattern 0.6mm×60mm                                       |
| 4               | Adhesion         |                                | Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. |
|                 | Initial Adhesion | $\geq 45.2\text{N}$            | Solder: 96.5Sn/0.5Cu Mildly activated flux used.              |
|                 | Ageing Adhesion  | $\geq 32\text{N}$              | Aging conditions: 150°C, 24 hours                             |

### Save Conditions And Validity Period :

The product should be stored in a sealed environment at 5-25°C. The shelf life is 1 year from the date of shipment.

### Packaging Method :

Standard packaging: 1000g per can. Samples are available in 200g small cans.